

Lab 2 Q3D Package Cross-Section Modeling

Tool used: Ansys Elctronic Desktop (AEDT) 2022 R2

File name: package_Q3D.aedt

Lab2

Die:

- Material : Silicon (other options available: glass, Au)
- Dimensions : 2 mm x 2 mm
- Die Height : 150 micron

Substrate:

- Material : FR4 (other options available: laminate, BT_system)
- Dimensions : 4 mm x 4 mm
- Height : 400 micron

Die Attach:

- Material : Modified Epoxy, relative permittivity: 4.2 (other options available: FR4, kevalar)
- Dimensions : 2mm x 2mm
- Thickness : 100 micron

Die Bond Pads:

- Material : Copper
- Dimensions : 0.2mm x 0.2mm
- Thickness : 5 micron
- Pitch: 0.2mm

Substrate Bond Pads:

- Material : Copper
- Dimensions : 0.2mm x 0.2mm

- Thickness : 10 micron
- Pitch: 0.2mm

Bond Wire:

- Material : Au (other options available: Copper)
- Type: JEDEC 5-point

Mold Compound:

- Material : Epoxy_kevalar_xy (other options available:)
- Thickness : 1.5mm







